ABSTRACT

A package structure and a package component are provided. The package structure includes: dielectric layers; first re-distribution layers, located in the dielectric layers; second re-distribution layers, located on the first re-distribution layers, where the first re-distribution layers are electrically connected to the second re-distribution layers, and the tops of the second re-distribution layers protrude from the dielectric layers; chips, located on the dielectric layers; and wires, connecting the chips to the second re-distribution layers.

[Fig. 1]